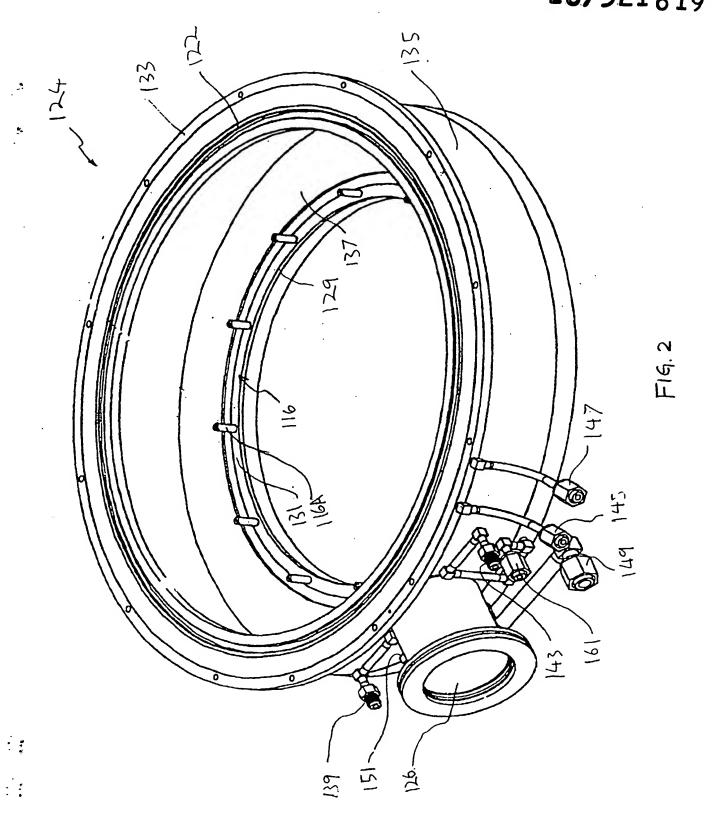


FIG. 1



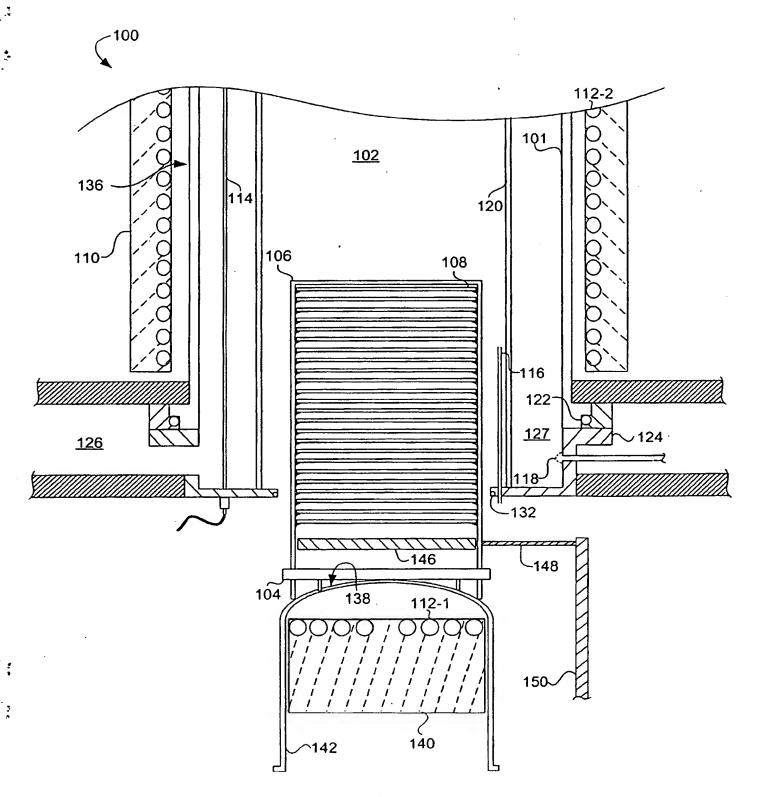
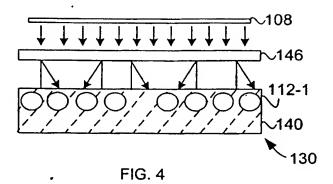


FIG. 3



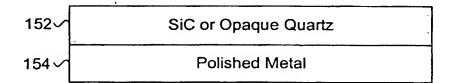


FIG. 5

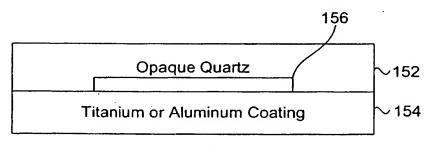
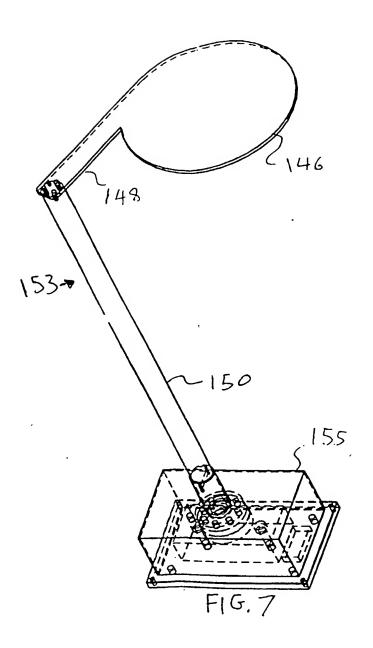


FIG. 6



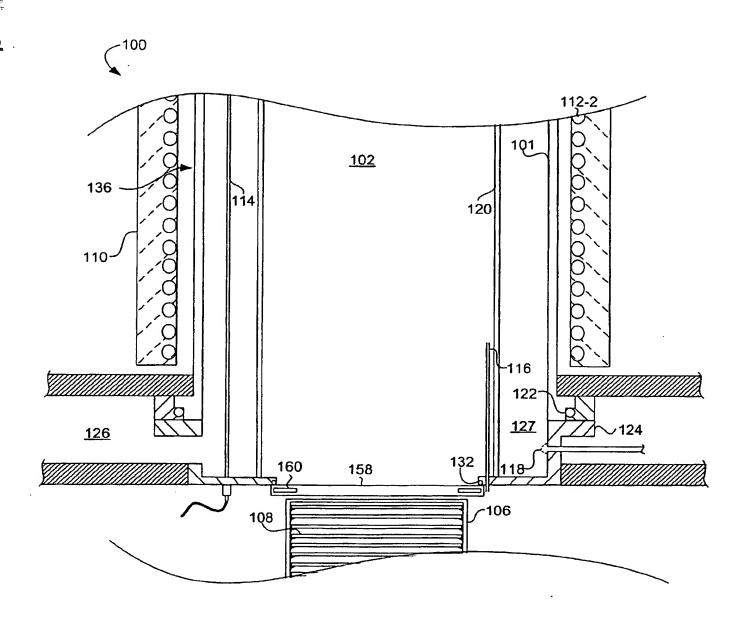
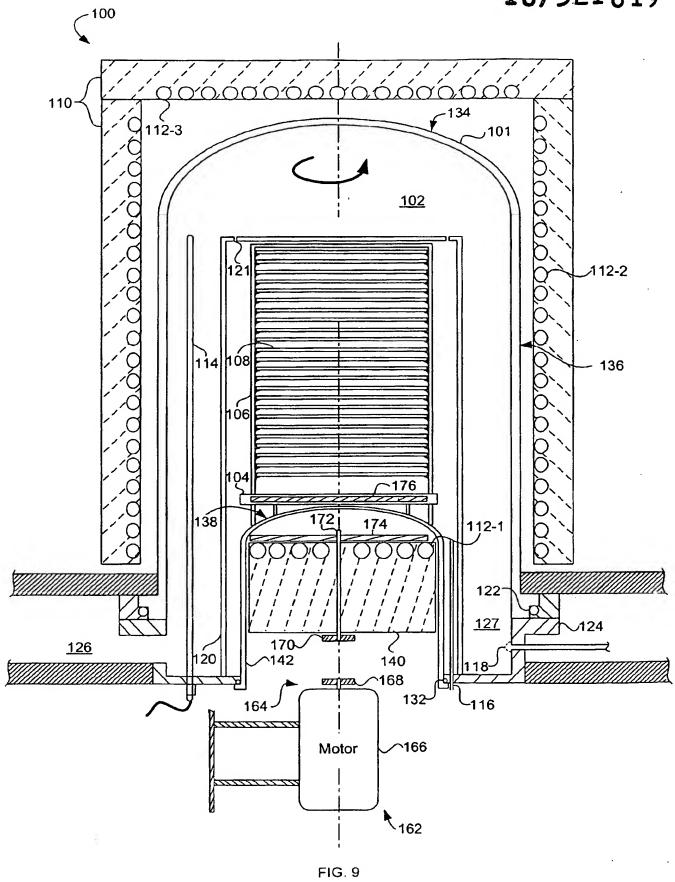


FIG. 8



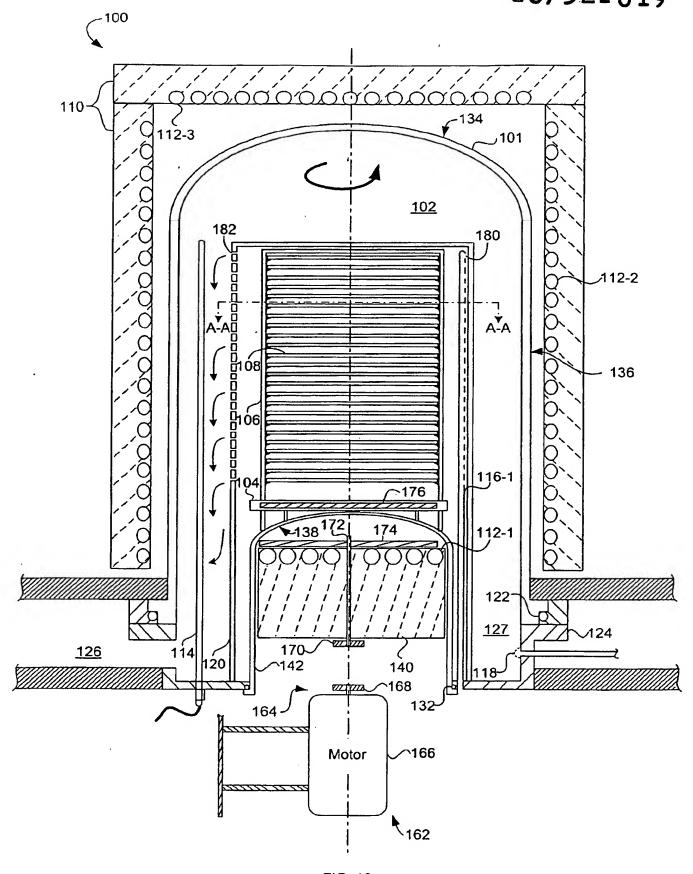


FIG. 10

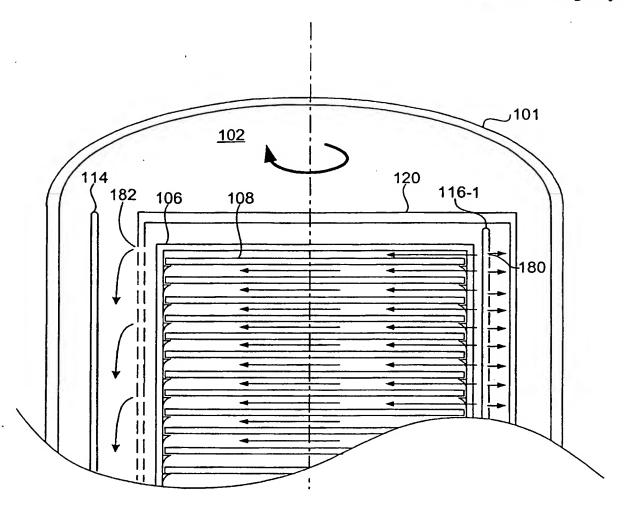


FIG. 11

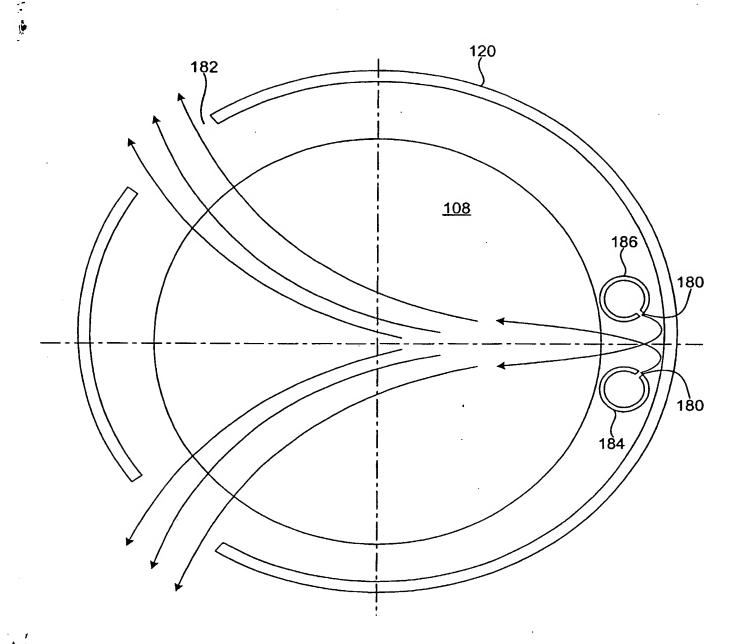


FIG. 12

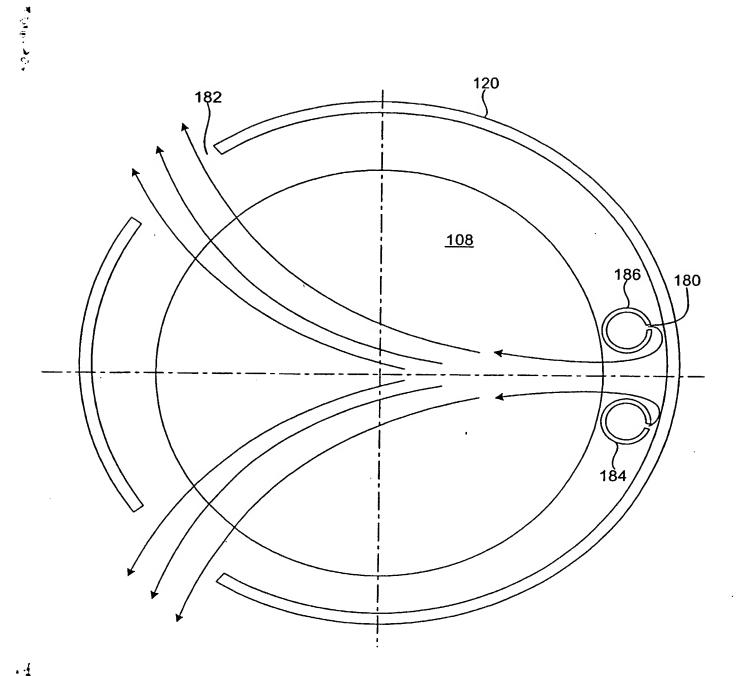


FIG. 13

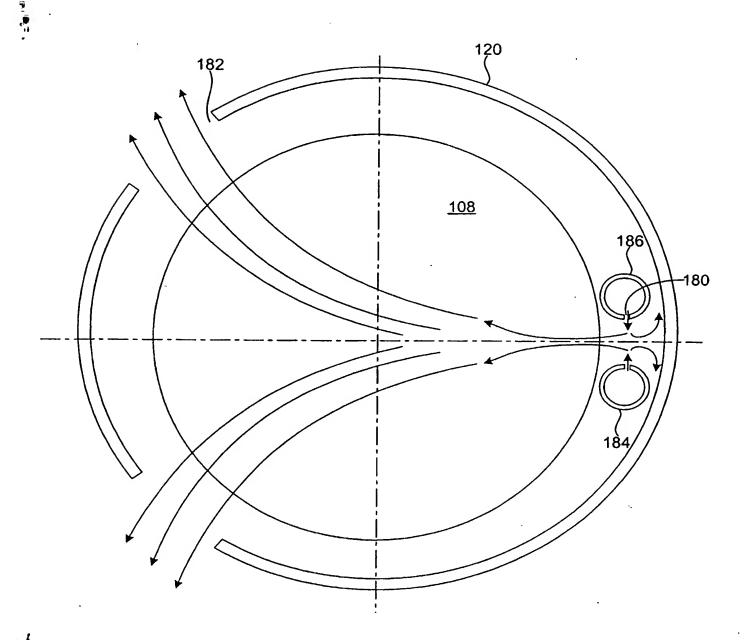


FIG. 14

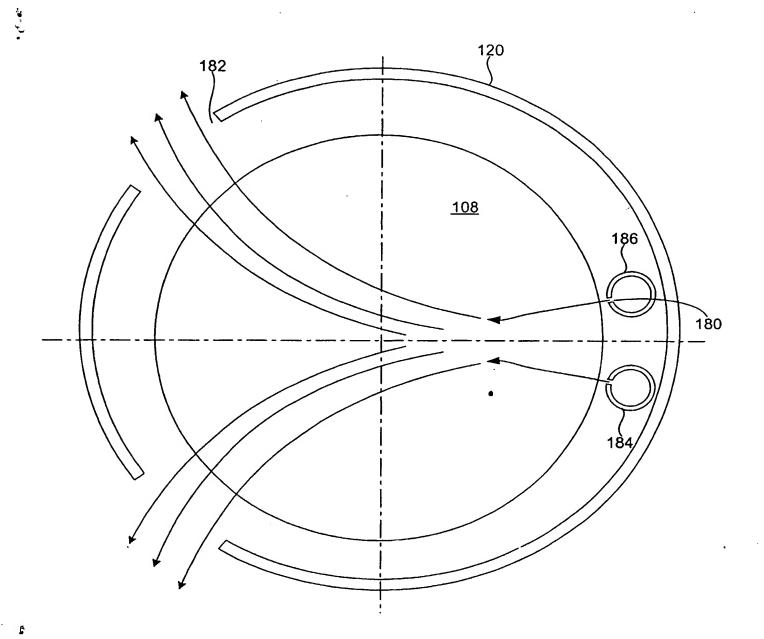


FIG. 15

* 37

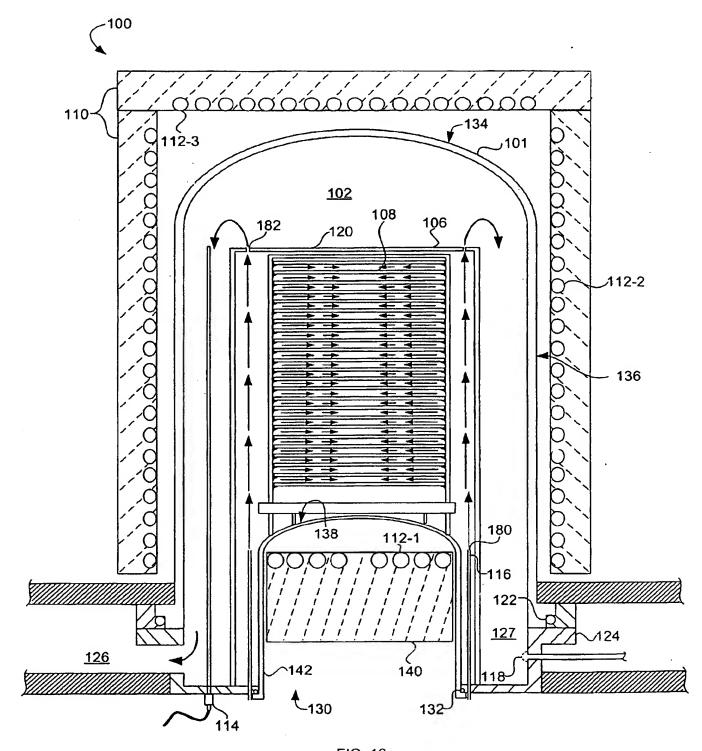


FIG. 16

3

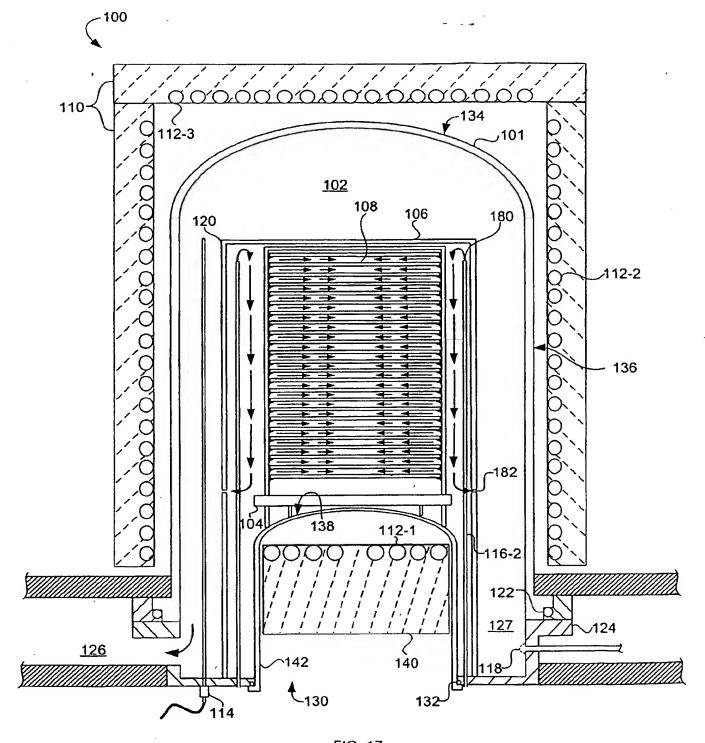
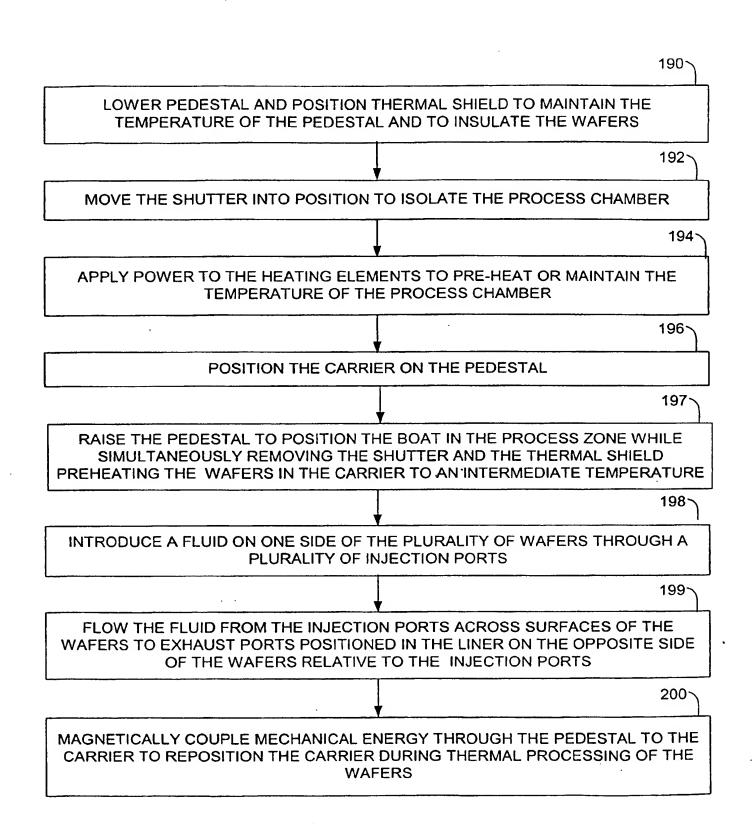


FIG. 17



202-Providing An Apparatus Having A Process Chamber No Larger Than Necessary To Accommodate The Carrier With The Wafers Held Therein 204-Heating The Process Chamber To Provide A Process Zone Therein Having A Substantially Isothermal Environment At A Desired Temperature 206-Lowering The Pedestal 208-Moving The Thermal Shield Into A Position To Reflect Heat From The Heating Element Back To The Pedestal To Maintain The Temperature Thereof 210-Moving The Shutter To Isolate The Process Chamber And Maintain The Temperature Thereof 212-Positioning The Carrier On The Pedestal 214 Moving The Thermal Shield 216 Preheating The Wafers In The Carrier To An Intermediate Temperature While Simultaneously Raising The Pedestal To Position The Carrier In The Process Zone 218-Positioning The Carrier In The Process Zone To Thermally Process The Wafers 220~ Introducing A Fluid On One Side Of Wafers Through Injection Ports Positioned Relative Thereto 222-Flowing The Fluid Directly Across Surfaces Of The Wafers From The Injection Ports To **Exhaust Ports In The Chamber Liner** 224-Magnetically Coupling Mechanical Energy Through The Pedestal To The Carrier To Reposition The Carrier During Thermal Processing Of The Wafers